

Bill of Materials

TI DESIGNS

TIPD118: Bandpass Filtered -40dB Attenuator Reference Design

Item #	Quantity	Value	Designator	Description	Manufacturer	Part Number	Supplier Part Number 1
1	1	C1		1uF	MuRata	GRM31CR72A105KA01L	490-3909-1-ND
2	1	C2		1500pF	MuRata	GRM2165C2A152JA01D	GRM2165C2A152JA01D-ND
3	2	C3, C7		10uF	AVX	TPSE106K050R0400	478-3361-1-ND
4	4	C4, C6, C8, C12		0.1uF	MuRata	GRM21BR71H104KA01L	490-1666-1-ND
5	2	C5, C11		100pF	MuRata	GRM2165C1H101JA01D	490-1615-1-ND
6	1	C9		0.068uF	MuRata	GRM31C5C1H683JA01L	490-3360-1-ND
7	1	C10		0.1uF	TDK Corporation	CGJ5L2C0G1H104J160AA	445-8219-1-ND
8	2	J1, J4		Connector, TH, SMA	Emerson Network Power	142-0701-201	J500-ND
9	4	J2,J3,J5,J6		Standard Banana Jack, Uninsulated, 5.5mm	Keystone	575-4	575-4K-ND
10	1	R1		100k	Susumu Co Ltd	RG2012P-104-B-T5	RG20P100KBCT-ND
11	1	R2		1.00k	Susumu Co Ltd	RG2012P-102-B-T5	RG20P1.0KBCT-ND
12	1	R3		49.9	Vishay Thin Film	PAT0805E49R9BST1	PAT49.9BCT-ND
13	1	R4		8.2	Yageo	RJ0805FRE078R2L	311-8.2VCT-ND
14	1	R5		1.00k	Vishay-Dale	CRCW08051K00FKEA	541-1.00KCCT-ND
15	3	TP1,TP7,TP8		White	Keystone	5002	5002K-ND
16	1	TP2		Red	Keystone	5000	5000K-ND
17	4	TP3, TP4, TP5, TP6		Black	Keystone	5001	5001K-ND
18	1	TP9		Yellow	Keystone	5004	5004K-ND
19	1	U1		IC OPAMP AUDIO 40MHZ SGL 8SOIC	Texas Instruments	OPA1611AID	296-24958-5-ND

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